

Dual Enhancement Mode MOSFET (N- and P-Channel)

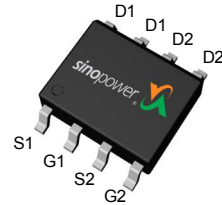
Features

- N-Channel
20V/9.5A,
 $R_{DS(ON)} = 14m\Omega(max.) @ V_{GS} = 4.5V$
 $R_{DS(ON)} = 18m\Omega(max.) @ V_{GS} = 2.5V$
- P-Channel
-20V/-6A,
 $R_{DS(ON)} = 45m\Omega(max.) @ V_{GS} = -4.5V$
 $R_{DS(ON)} = 65m\Omega(max.) @ V_{GS} = -2.5V$
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free and Green Devices Available
(RoHS Compliant)

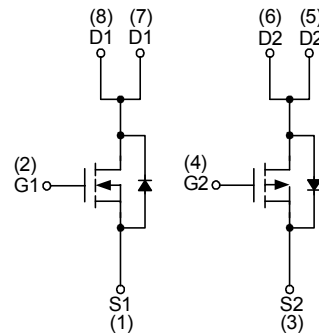
Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

Pin Description



Top View of SOP-8



N-Channel MOSFET P-Channel MOSFET

Ordering and Marking Information

SM2001CS □□-□□ □ Assembly Material Handling Code Temperature Range Package Code	Package Code K : SOP-8 Operating Junction Temperature Range C : -55 to 150 °C Handling Code TR : Tape & Reel Assembly Material G : Halogen and Lead Free Device
SM2001CS K :  2001 XXXXX	XXXXXX - Lot Code

Note : SINOPOWER lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. SINOPOWER lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. SINOPOWER defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

SINOPOWER reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Channel 1	Channel 2	Unit
Common Ratings (T _A =25°C Unless Otherwise Noted)					
V _{DSS}	Drain-Source Voltage		20	-20	V
V _{GSS}	Gate-Source Voltage		±12	±12	
T _J	Maximum Junction Temperature		150		°C
T _{STG}	Storage Temperature Range		-55 to 150		
I _S	Diode Continuous Forward Current	T _A =25°C	1.8	-1.2	A
I _D	Continuous Drain Current	T _A =25°C	9.5	-6	
I _{DM} ^a	Pulsed Drain Current	T _A =25°C	30	-20	
P _D	Power Dissipation	T _A =25°C	2	2	W
		T _A =70°C	1.3	1.3	
R _{θJA}	Thermal Resistance-Junction to Ambient	t ≤ 10s	45	45	°C/W
		Steady State	62.5	62.5	
R _{θJL}	Thermal Resistance-Junction to Lead	Steady State	20	20	
I _{AS} ^b	Avalanche Current, Single pulse (L=0.1mH)		16	-15	A
E _{AS} ^b	Avalanche Energy, Single pulse (L=0.1mH)		12	11	mJ

Note a : Pulse width limited by max. junction temperature.

Note b : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^\circ\text{C}$).

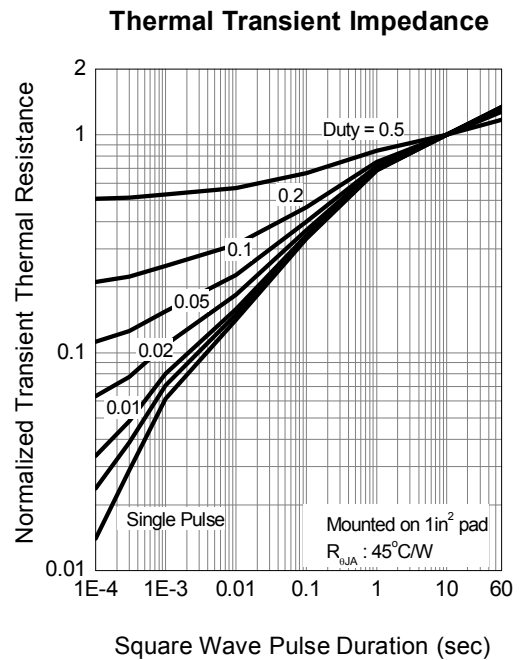
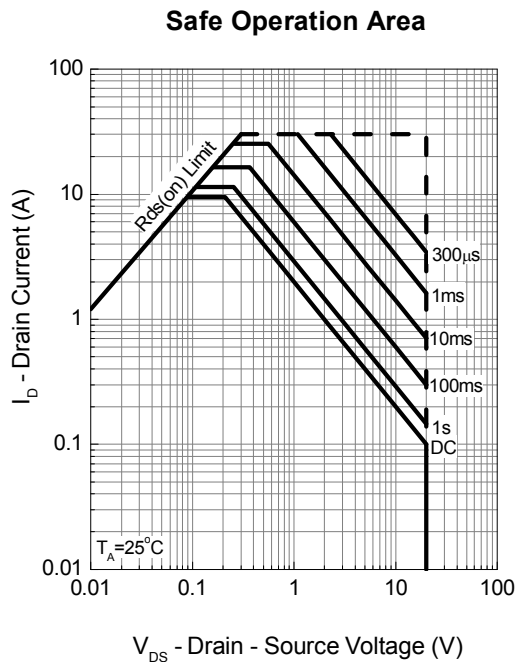
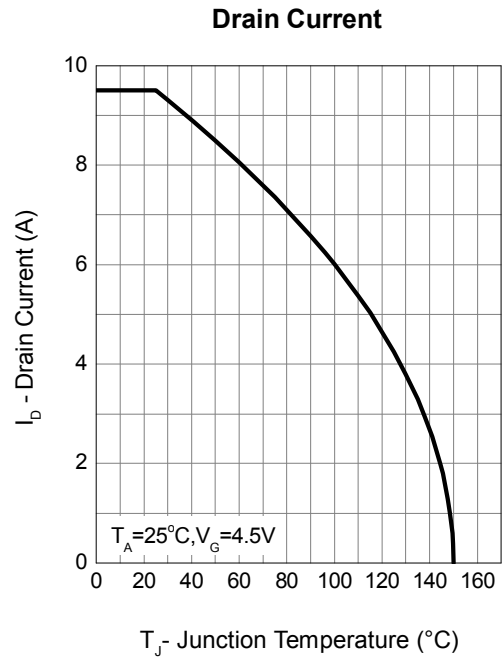
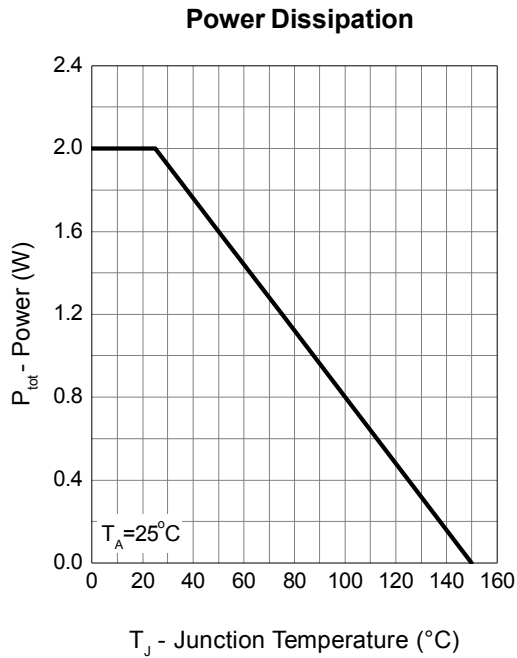
Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Channel 1			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =16V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	0.5	0.7	1.0	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} =4.5V, I _{DS} =9A	-	12	14	mΩ
		V _{GS} =2.5V, I _{DS} =6A	-	13.5	18	
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _{SD} =1.5A, V _{GS} =0V	-	0.67	1.1	V
t _{rr}	Reverse Recovery Time	I _{DS} =6A, dI _{SD} /dt=100A/μs	-	11.8	-	ns
Q _{rr}	Reverse Recovery Charge		-	3.6	-	nC
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	0.7	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V, Frequency=1.0MHz	-	795	-	pF
C _{oss}	Output Capacitance		-	160	-	
C _{rss}	Reverse Transfer Capacitance		-	118	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =10V, R _L =10Ω, I _{DS} =1A, V _{GEN} =4.5V, R _G =1Ω	-	10.2	19	ns
t _r	Turn-on Rise Time		-	16.1	30	
t _{d(OFF)}	Turn-off Delay Time		-	16.6	31	
t _f	Turn-off Fall Time		-	3.6	7	
Gate Charge Characteristics						
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V, I _{DS} =6A	-	8.7	-	nC
Q _{gs}	Gate-Source Charge		-	1.25	-	
Q _{gd}	Gate-Drain Charge		-	3	-	
Q _{gth}	Threshold Gate Charge		-	0.54	-	

Electrical Characteristics (Cont.) ($T_A = 25^\circ\text{C}$ unless otherwise noted)

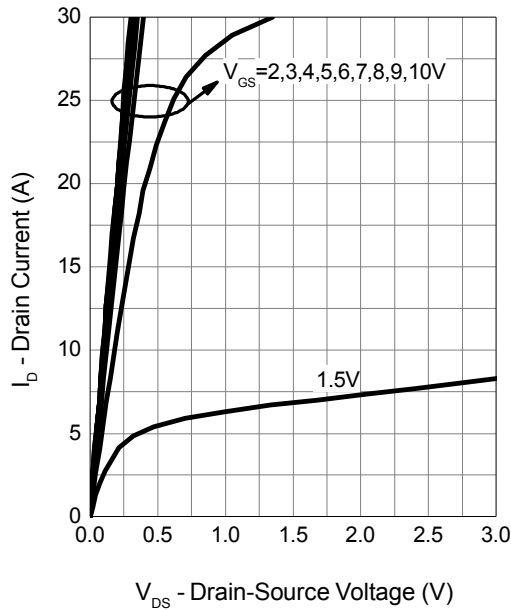
Symbol	Parameter	Test Conditions	Channel 2			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =-250μA	-20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-16V, V _{GS} =0V	-	-	-1	μA
		T _J =85°C	-	-	-30	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =-250μA	-0.5	-0.7	-1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±12V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)}	Drain-Source On-state Resistance	V _{GS} =-4.5V, I _{DS} =-6A	-	36	45	mΩ
		V _{GS} =-2.5V, I _{DS} =-4A	-	50	65	
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _{SD} =-1.2A, V _{GS} =0V	-	-0.7	-1	V
t _{rr}	Reverse Recovery Time	I _{sd} =-6A, dI _{SD} /dt=100A/μs	-	12	-	ns
Q _{rr}	Reverse Recovery Charge		-	4.5	-	nC
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	3.5	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-10V, Frequency=1.0MHz	-	590	-	pF
C _{oss}	Output Capacitance		-	122	-	
C _{rss}	Reverse Transfer Capacitance		-	92	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =-10V, R _L =10Ω, I _{DS} =-1A, V _{GEN} =-4.5V, R _G =1Ω	-	8.4	16	ns
t _r	Turn-on Rise Time		-	14.1	26	
t _{d(OFF)}	Turn-off Delay Time		-	16	30	
t _f	Turn-off Fall Time		-	10.7	20	
Gate Charge Characteristics						
Q _g	Total Gate Charge	V _{DS} =-10V, V _{GS} =-4.5V, I _{DS} =-6A	-	7.68	-	nC
Q _{gs}	Gate-Source Charge		-	0.66	-	
Q _{gd}	Gate-Drain Charge		-	2.72	-	
Q _{gth}	Threshold Gate Charge		-	0.3	-	

N Channel Typical Operating Characteristics

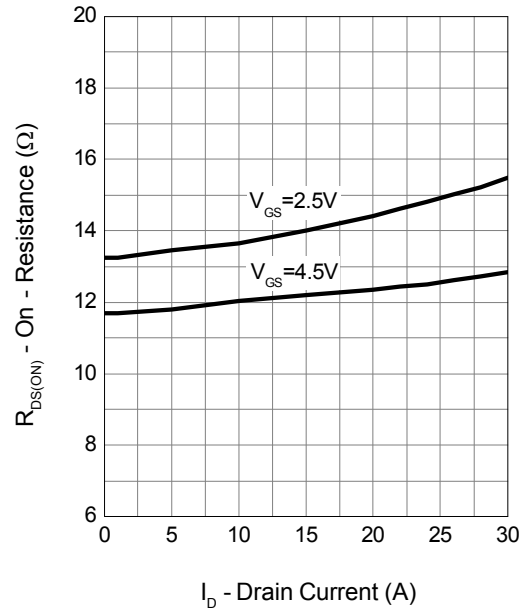


N Channel Typical Operating Characteristics (Cont.)

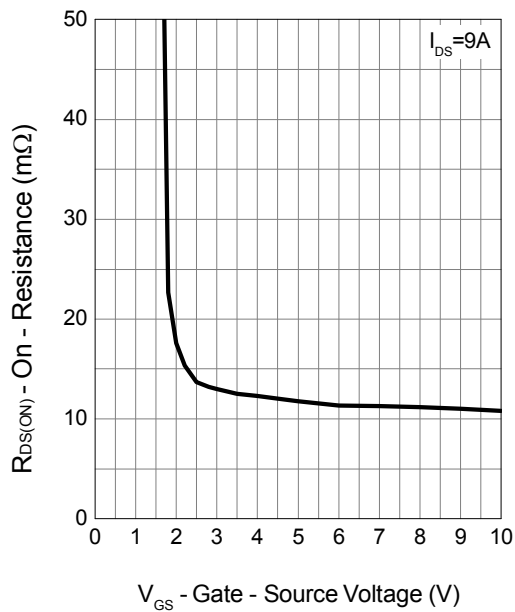
Output Characteristics



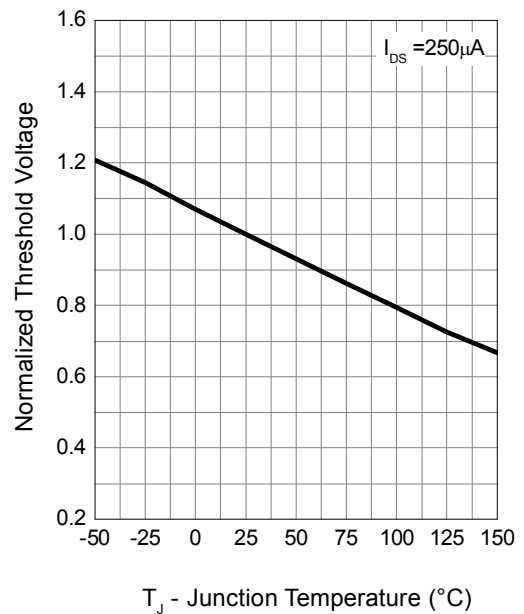
Drain-Source On Resistance



Transfer Characteristics

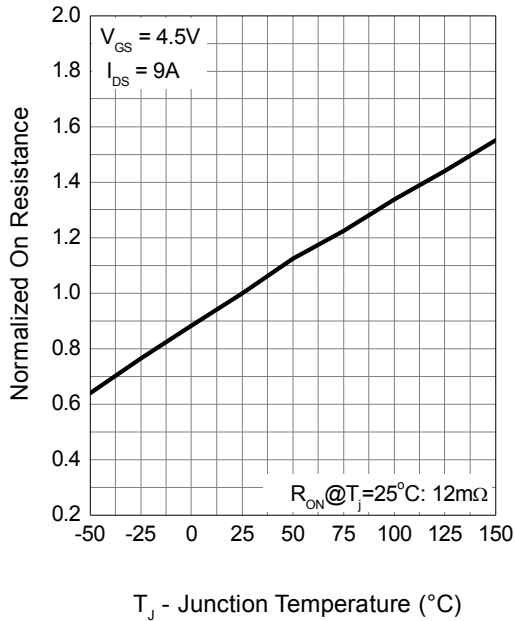


Gate Threshold Voltage

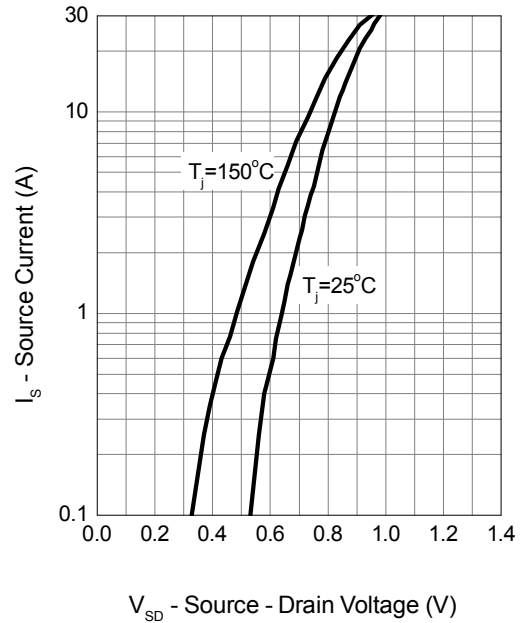


N Channel Typical Operating Characteristics (Cont.)

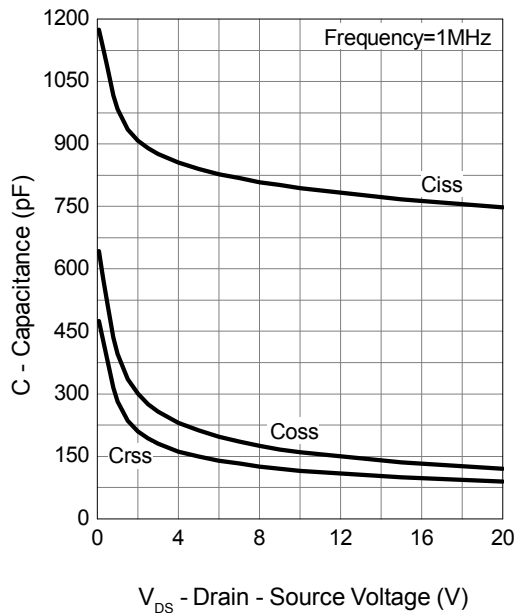
Drain-Source On Resistance



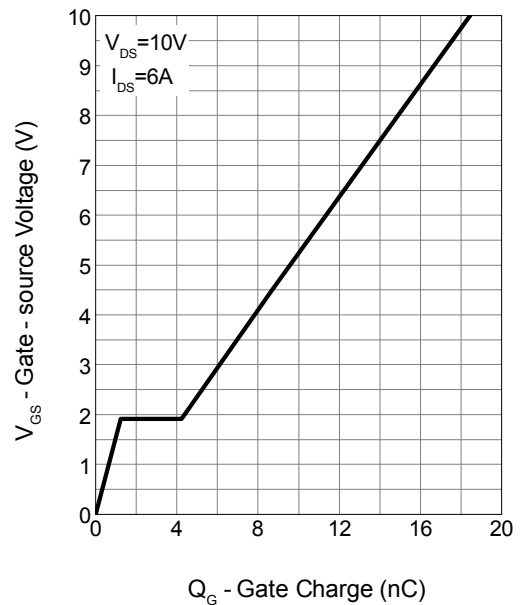
Source-Drain Diode Forward



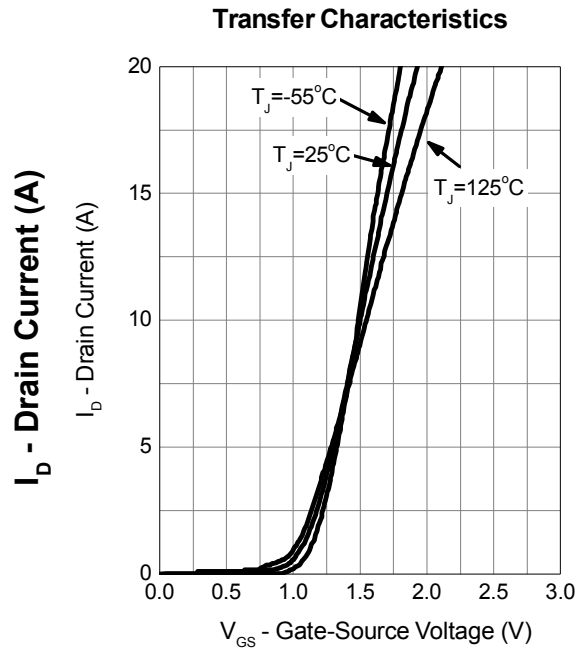
Capacitance



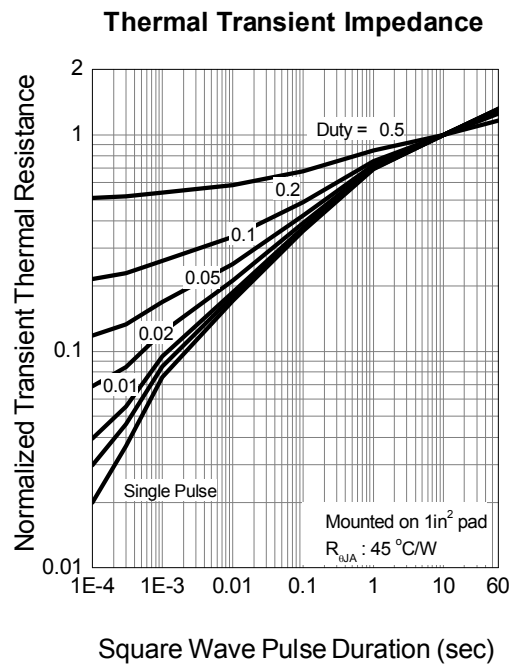
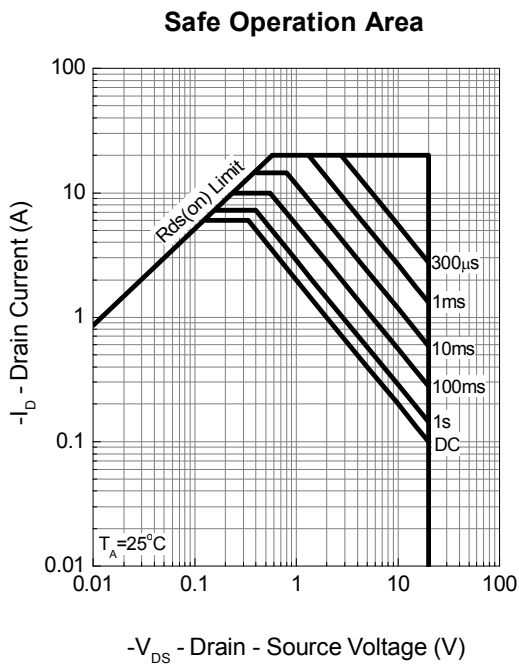
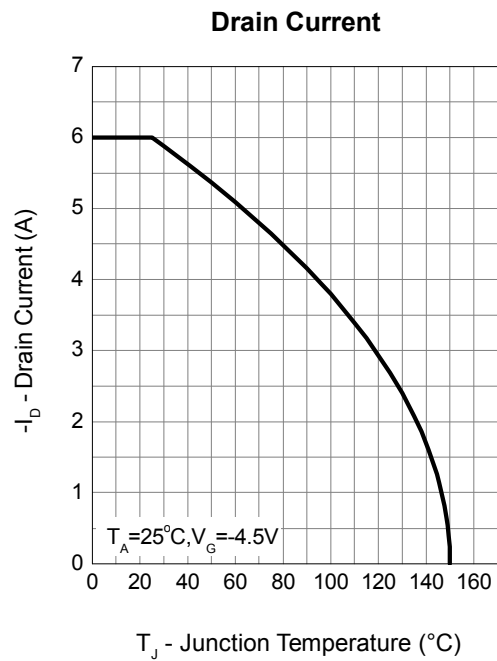
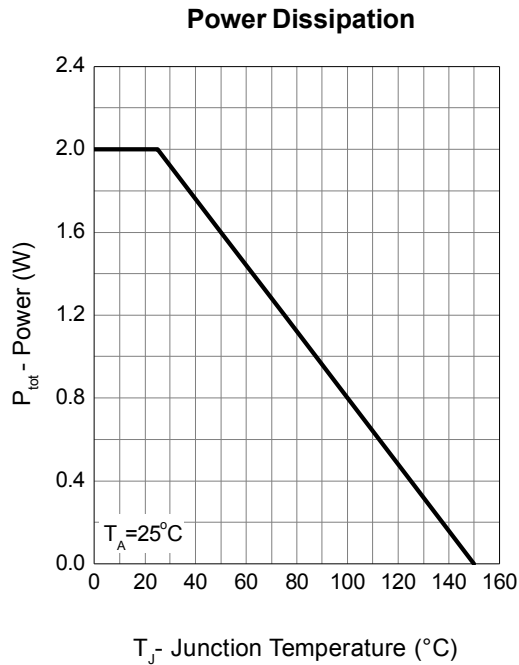
Gate Charge



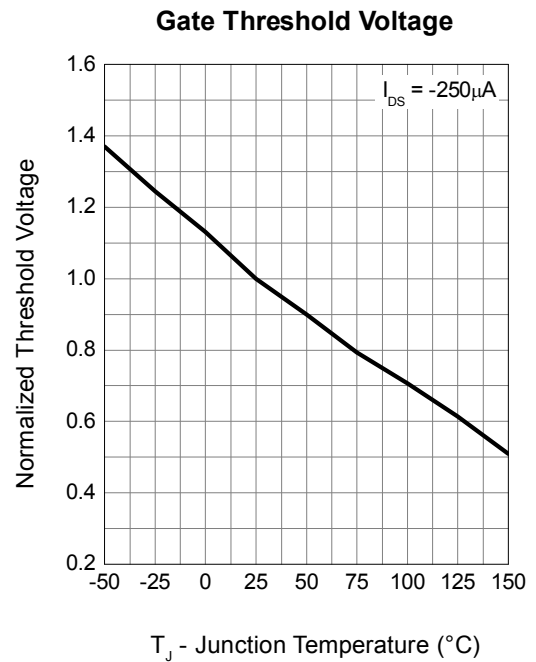
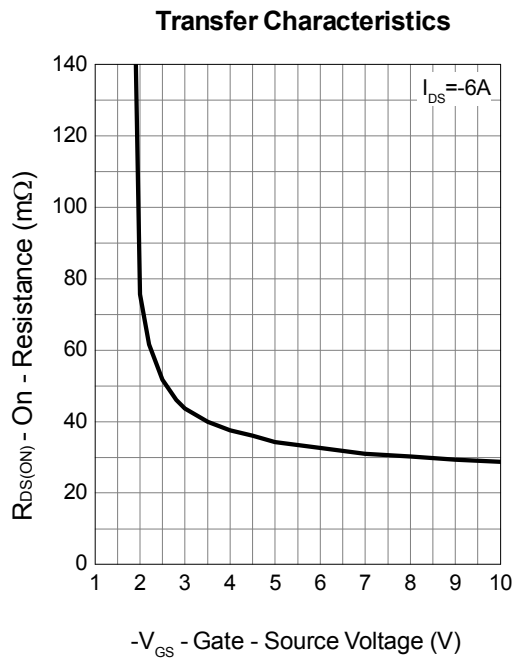
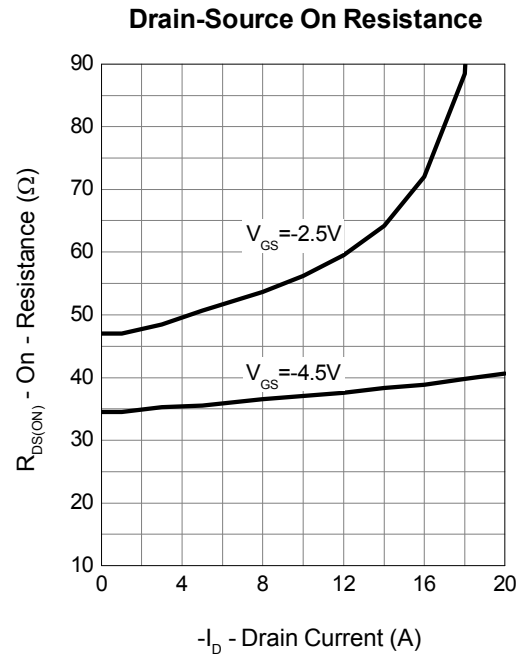
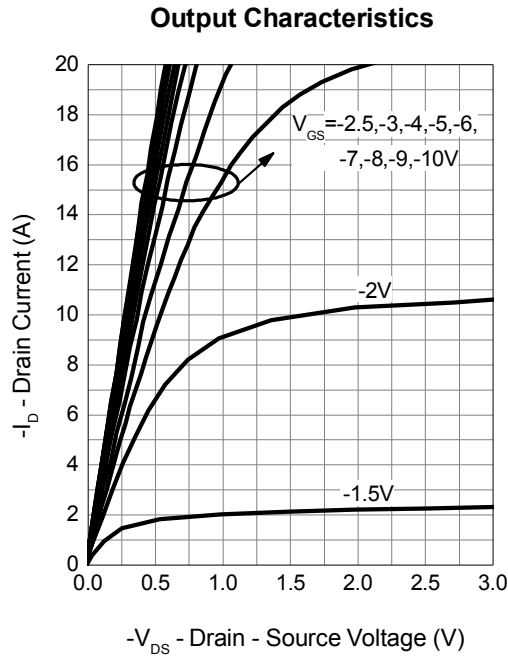
N Channel Typical Operating Characteristics (Cont.)



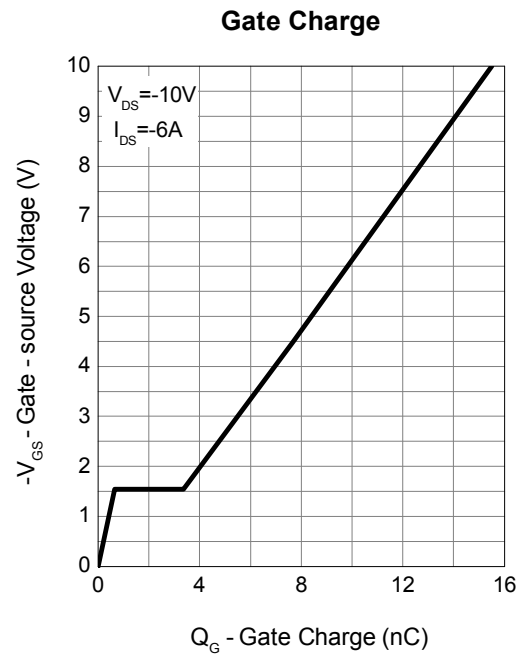
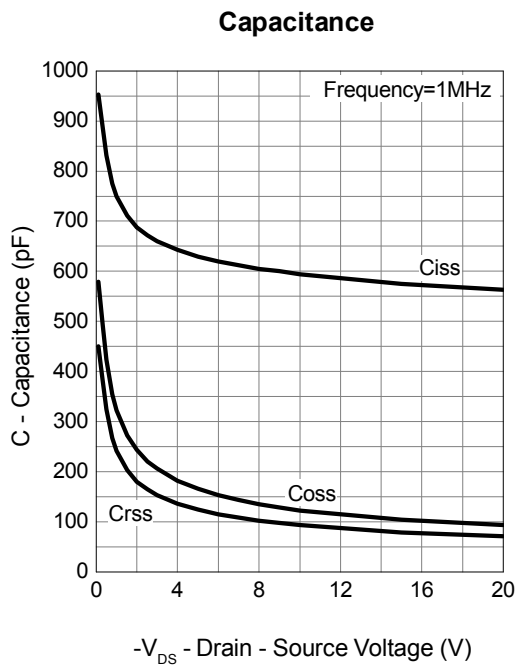
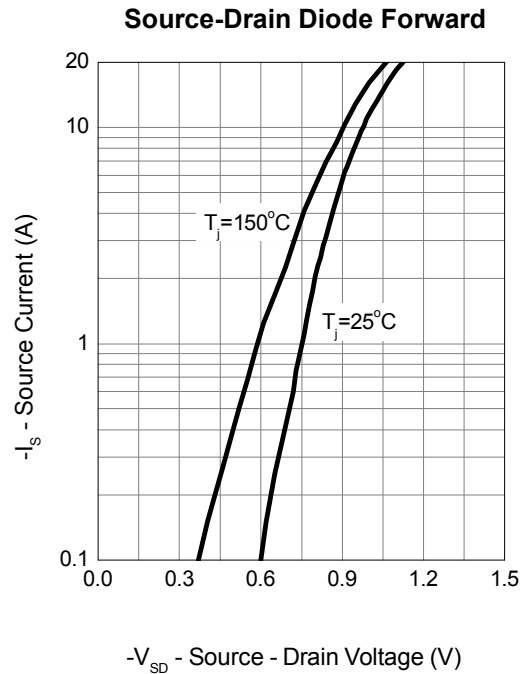
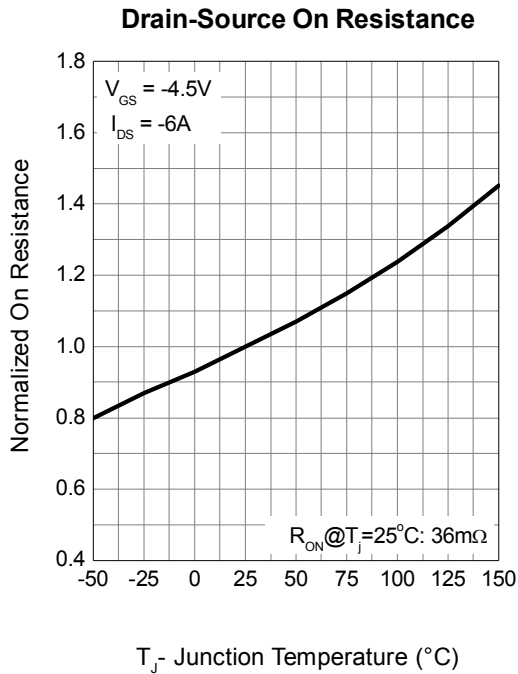
P Channel Typical Operating Characteristics

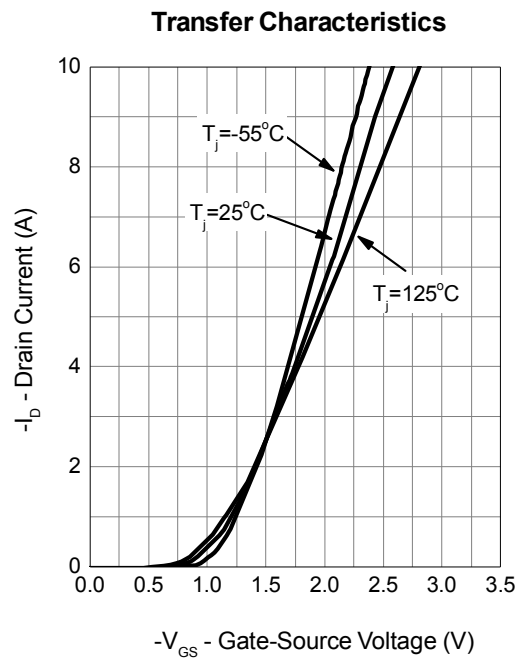


P Channel Typical Operating Characteristics (Cont.)



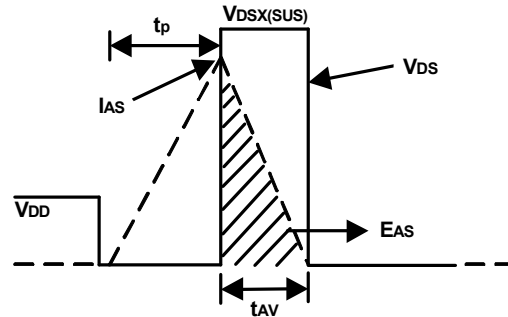
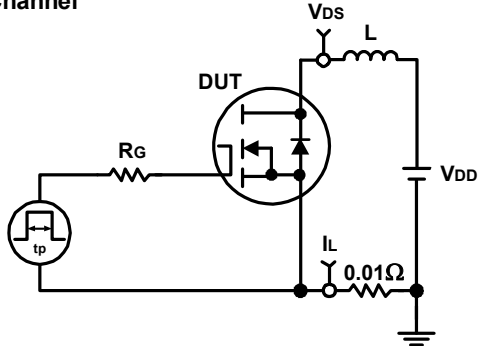
P Channel Typical Operating Characteristics (Cont.)



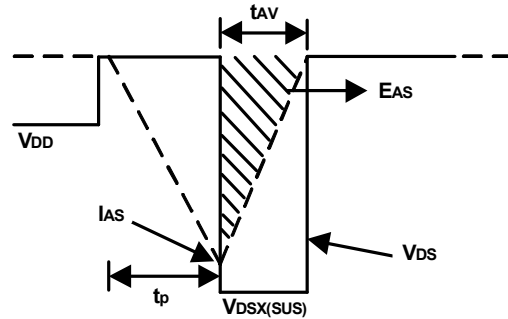
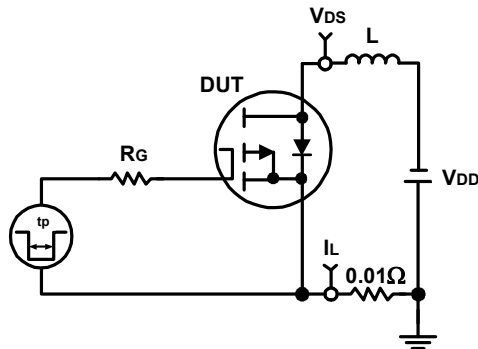
P Channel Typical Operating Characteristics (Cont.)

Avalanche Test Circuit and Waveforms

N Channel

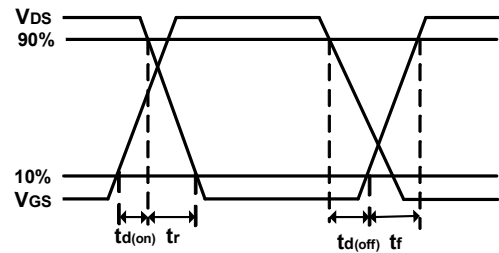
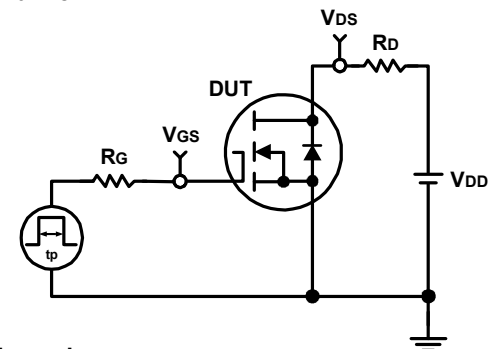


P Channel

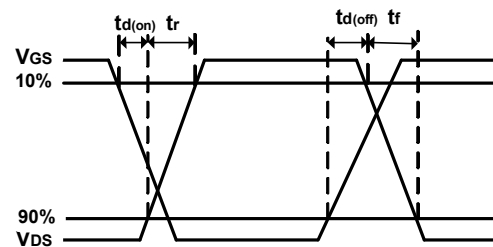
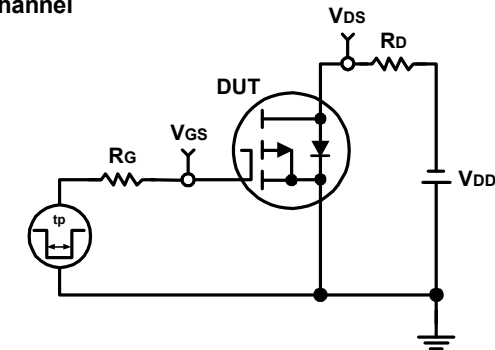


Switching Time Test Circuit and Waveforms

N Channel



P Channel



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Figure 1 illustrates the temperature profile of a typical heat pump. The main graph plots Temperature (Y-axis) against Time (X-axis). The temperature starts at 25°C, rises to a peak T_p , and then falls. Key points on the Y-axis include T_c (critical temperature), $T_c - 5^\circ\text{C}$, T_{smax} , T_{smin} , and T_L . The preheat area is indicated between T_{smin} and T_{smax} . The time from 25°C to peak is labeled "Time 25°C to Peak". The ramp up rate is 3°C/s and the ramp down rate is 6°C/s. The peak duration t_p is shown. Two inset graphs show the temperature profile for Supplier ($T_p \geq T_c$) and User ($T_p \leq T_c$) scenarios, both showing a peak at $T_c - 5^\circ\text{C}$.

Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	1000 Hrs, 80% of VDS max @ T_{jmax}
HTGB	JESD-22, A108	1000 Hrs, 100% of VGS max @ T_{jmax}
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C

Customer Service

Sinopower Semiconductor, Inc.

5F, No. 6, Dusing 1St Rd., Hsinchu Science Park,

Hsinchu, 30078, Taiwan

TEL: 886-3-5635818 Fax: 886-3-5635080